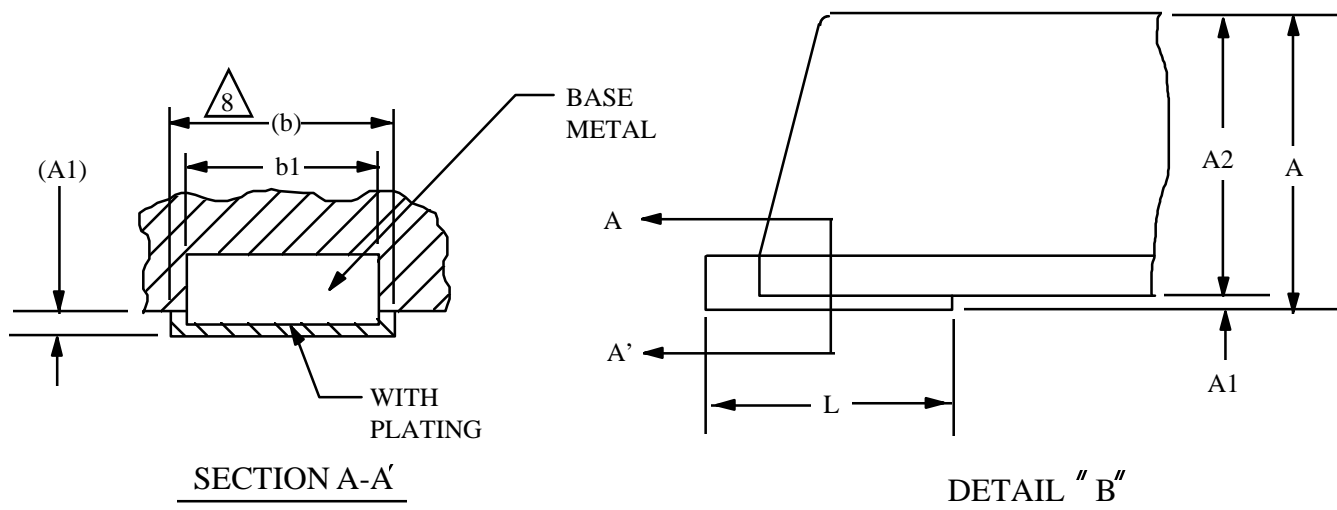
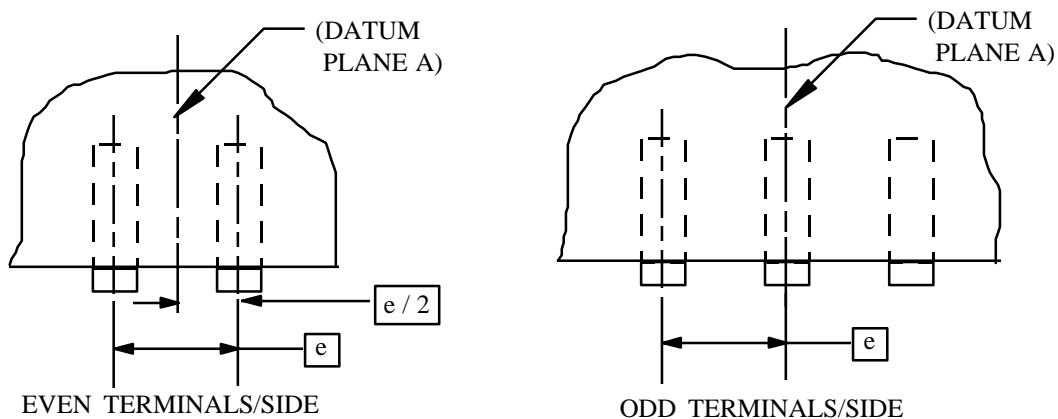
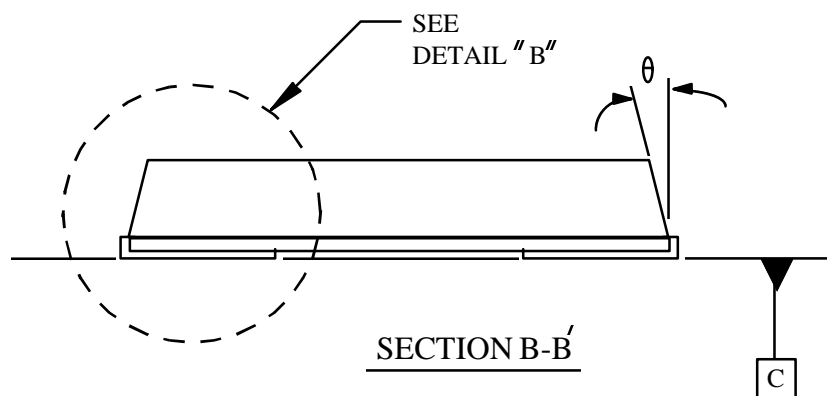



PATENT CLAIM 9

JEDEC SOLID STATE PRODUCT OUTLINES	THIS <b>REGISTERED OUTLINE</b> HAS BEEN PREPARED BY THE JEDEC JC-II COMMITTEE AND REFLECTS A PRODUCT WITH ANTICIPATED USAGE IN THE ELECTRONICS INDUSTRY;CHANGES ARE LIKELY TO OCCUR.				
TITLE : PLASTIC ULTRA-THIN SMALL OUTLINE NO-LEAD PACKAGE	JESD-30 DESIGNATOR R-PDSO-N	ISSUE B	DATE Nov 97	MO-197	SHEET 1 OF 4



JEDEC SOLID STATE PRODUCT OUTLINES	TITLE : PLASTIC ULTRA-THIN SMALL OUTLINE NO-LEAD PACKAGE	ISSUE B	DATE Nov 97	MO-197	SHEET 2 OF 4
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SYMBOL	DIMENSIONS IN MILLIMETER									NOTE
	VARIATIONS									
	AA 			AB			AC			
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
A				0.65	—	0.80	—	—	0.95	
A1				0.00	0.02	0.05	0.00	—	0.05	
A2				0.65	0.70	0.75	0.65	0.80	0.90	
b				0.27	0.32	0.37	0.25	—	0.45	8
b1				0.27	0.30	0.33	0.25	0.35	0.40	8
D				10.75 BSC.			13.60 BSC.			4,5
E				10.10 BSC.			7.20 BSC.			
E1				9.90	10.00	10.10	6.85	7.00	7.15	4,5
e				0.50 BSC.			0.80 BSC.			
L				0.40	0.50	0.70	0.55	0.70	0.85	
θ				2°	5°	8°	3°	—	16°	
aaa				0.05			0.20			
N				40			28			7
Notes				1,3			1,3			
REF	11-472 / 11-498			11-472			11-475 / 11-498			
Issue	A/B			A			A/B			

JEDEC SOLID STATE PRODUCT OUTLINES	TITLE : PLASTIC ULTRA-THIN SMALL OUTLINE NO-LEAD PACKAGE	ISSUE  B	DATE  Nov 97	MO-197	SHEET  3 OF 4
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NOTES :

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M-1994.

△2. DATUM A AND B TO BE DETERMINED AT DATUM C.

3. ALL DIMENSIONS ARE IN MILLIMETERS.

△4. DIMENSION D DOES NOT INCLUDE MOLD PROTRUSIONS OR GATE BURRS. MOLD FLASH AND GATE BURRS SHALL NOT EXCEED 0.20mm PER SIDE. DIMENSION E1 DOES NOT INCLUDE INTERLEAD MOLD FLASH. INTERLEAD MOLD FLASH SHALL NOT EXCEED 0.10mm PER SIDE.

△5. TO BE DETERMINED AT SEATING PLANE DATUM C.

△6. THE LEAD #1 IDENTIFIER AND LEAD NUMBERING CONVENTION SHALL CONFORM TO JESD 95-1 SPP-012. DETAILS OF LEAD #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE LEAD #1 IDENTIFIER MAY BE EITHER A MOLDED OR A MARKED FEATURE.

7. N IS THE MAXIMUM NUMBER OF LEADS.

△8. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10mm AND 0.25mm FROM THE LEAD TIP. DIMENSION A1 IS PRIMARILY TERMINAL PLATING ; BUT MAY, OR MAY NOT INCLUDE A SMALL PROTRUSION OF TERMINAL BELOW THE BOTTOM SURFACE OF THE PACKAGE.

PATENT CLAIMS

△9. FUJITSU HAS STATED THAT U.S. PATENT NUMBER 5,519,251 MAY RELATE TO A CERTAIN IMPLEMENTATION OF THIS PACKAGE OUTLINE. LG SEMICON CORPORATION HAS STATED THAT U.S. PATENT 5,363,279 MAY RELATE TO CERTAIN FEATURES OF THIS PACKAGE OUTLINE.

△10. VARIATION AA(46LEAD) HAS BEEN DELETED FROM THIS REGISTRATION AND TRANSFERRED TO MO-196 AS VARIATION FHE. AA CANNOT BE USED FOR ANY FUTURE VARIATION IN THIS REGISTRATION.

JEDEC SOLID STATE PRODUCT OUTLINES	TITLE : PLASTIC ULTRA-THIN SMALL OUTLINE NO-LEAD PACKAGE	ISSUE  B	DATE  Nov 97	MO-197	SHEET  4 OF 4
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